

# Products Specification For Approval

Customer: VIP Customer.

Customer's Products Name	ZHMP Products Name
0630-101M	MPH0630-101M



#### ZonHonMonPon ELECTRONIC TECHNOLOGIES

Approved	Checked	Designed
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## 1. Scope:

This specification applies the Shielded construction chip inductor MPH0630-101M.

## 2. Outline:

The products are used as choke coils for DC/DC converter and consist of Iron Powder、 coil and terminals.

## 3. Safety Specification:

The products shall be used as secondary circuit parts, thus are not applied by any specific safety standards.

## 4. Specification:





А	6.95±0.35	D	3.0±0.2
В	6.6±0.2	E	1.5±0.5
С	3.0 Max.	F	3.5Ref.

#### 4.2. Main parts list

No.	Part name	Material	Quantity
1	Iron Powder	FeSiCr Iron Powder or Equivalent	0.55 g
2	Coil	Cu/E200/G2Polyurethane enameled or Equivalent	1set
3	Ноор	C5191H or Equivalent	1set
4	Glue	Resin	1set

#### .3. Pin Connection:



#### 4.4. Recommended Land Pattern:



Ι	3.7 Ref.
J	8.4 Ref.
Н	3.5 Ref.

#### 4.5. Electrical Specifications:

Part Number	Rated Inductance (1) (µH)	Test Condition	DC Resistance (mΩ)	Self -Resonant Frequency (MHz) Min.	Isat (2) Amperes (A)	Irms(3) Amperes (A)	Part Marking Designator
MPH0630-101M	100±20%	100kHz,1Vrms	858Max.715Typ.		1.2	1.0	101

(1) Open Circuit Inductance Test Parameters: 100kHz, 1.0Vms, 0.0Adc.

(2) Isat Amperes Typical for approximately 30% roll off (@25°C)

(3) Irms: current for an approximate  $\Delta T$  of 40°C without core loss

s(Ta=25°C). It is recommended that the temperature of the part not exceed 125°C. PCB layout, trace thickness and width, air-flow, and

proximity of other heat generating components will affect the temperature rise. It is recommended that the temperature of the part not exceed 125°C under worst case operating conditions verified in the end application. (4) Rated current: Isat and Irms whichever is lower.

Note: The rated current is subject to change depending on the cooling



### 4.6. Ordering Code & Explanation of Part Numbers:



#### 4.7. Bias Characteristic





## 5.Package Specification:

- 5.1. Taping Specification: 5.1.1.Reel Dimension (Unit: mm) :





5.1.2. Taping Dimension (Unit: mm) :



STA														
YLE	Q'TY (PCS)	А	В	С	D	G	Т	A0	B0	K0	t	Р	Po	P2
13"	1500	330	100	13.5 ±0.5	16.0 ±0.2	16.4 ±0.5	22.4 ±2.0	7.20 ±0.1	7.90 ±0.1	3.20 ±0.1	0.40 ±0.05	12.0 ±0.1	4.0 ±0.1	2.0 ±0.1

5.1.3. Tensile Strength: 5.1.3.1. Plastic tape :

 $\geq$  10N ( $\geq$  1.0kgf)

- 5.1.3.2.Material : PS 5.1.3.3.Cover tape :  $\geq$  5N ( $\geq$  0.5kgf)
- 5.1.4. Tensile Strength of Cover Tape (Ref.): F=0.2 ${\sim}0.9N$

Angel of pull 0  $\sim\,$  15  $\,^\circ\,$  opposite the forward direction, Velocity of pull: 300 mm/min.



5.1.5.Packing Style of Taping

(Unit: mm)





5.1.6. Packaging Style of Products:



## TAPE DIRECTION OF FEED

- 5.1.7. Packaging style of case
- 5.1.7.1. Packing cases are composed of the inner case and outer case.
- 5.1.7.2. Nine inners cases are put in an outer, thus 13,500 products put in an outer case.
- 5.1.7.3. Paper cushion are placed on the upper and bottom side in the outer case



1,500 pcs in 1 reel (inner) case







3 reels (inner) cases in 1 packaging (outer) case

5.1.8. Indication: 5.1.8.1. Label attached on reel:

**Production Label** 



P/N.:MPH0630-101M

## 

Qty.:1,500pcs



Made in China

5.1.8.1. Label attached on packaging (outer) case:

Production Label







Made in China

5.1.9. Notes:

5.1.9.1. This specification defines the standard packaging style and is subject to change depending on quantity or fractions.

5.1.9.2. Inside of cases shall be filled with cushions to keep the products stable.

5.1.9.3. Inspection Certificate: Attach size data and the electric characteristic result for each shipping lot as "Inspection Certificate".

# 6. Reliability data:

Item	Specified Value	Test Method and Remarks
1.Operating	-40°C∼+125°C	Including self-generated heat.
Temperature Range		
2. Storage Temperature	-40℃~+125℃	$0 \sim 40^{\circ}$ C for the product with taping.
Range		
3.External Appearance	The coil has no external defects.	On visual inspection.
4.Rated current	Within the specified tolerance	The maximum DC value having inductance decrease within
		specified value and temperature increase within $40^{\circ}$ by the
		application of DC bias
		Inductance decrease (Type: 30%)
5 Inductores	Within the energified telerance	LCP Motor: HP 4104A or equivelent 100KHz 0.25V
	Within the specified tolerance	DC obmmotor: TOS2001 or equivalent
		Impedence englyzer/meterial englyzer: UD42014
frequency		
		HP4194A, 4192A or equivalent.
8. I emperature		Measurement of inductance shall be taken at temperature
characteristic	Within±15% 0∼2000ppm/℃	range within -40 $\sim$ +125 $^{\circ}$ C.
		With reference to inductance value at +25 $^\circ\!\!\mathbb{C}$ , change rate
		shall be calculated.
		Change of maximum inductance deviation in step 1 to 5
		Temperature at step 1: 25℃
		Temperature at step 2: Minimum operating temperature
		Temperature at step 3: 25℃(Standard temperature)
		Temperature at step 4: Maximum operating temperature
		Temperature at step 5: 25 °C and the value calculate based
		on the value applicable in a normal temperature and normal
		humidity shall be $\Delta I/I_{exp} \leq \pm 15\%$
		Manually shall be $E_{1}$ $E_{2}$ $E_$
9. Resistance to flexure	Inductance change: Within±5.0%	i ne test samples shall be soldered to the test board by the
of substrate	There shall be no mechanical damage or	reflow.
	electrical damage	As illustrated below, apply force in the direction of the arrow
		indicating until deflection of the test board reaches to 3 mm.
		I est board size: 100°40*1.0 Test board material: glass
		epoxy-resin
		Solder cream thickness: 0.12mm.
		Keep time: 3~5seconds Speed:0.5mm/sec
		Force Rod 10 20
		R230
		Board
		Test Sample (1)
		$\begin{bmatrix} H_5 \\ H_2 \\ 45\pm 2mm \end{bmatrix} \begin{bmatrix} 100 & 0 \\ 45\pm 2mm \end{bmatrix} \begin{bmatrix} 100 & 0 \\ 45\pm 2mm \end{bmatrix}$
		Printed board thickness: 1.0mm
		Unit: mm



Item	Specified Value	Test Meth	od and Remarks		
10.Insulation resistance	NL	Between Coils			
11.Insulation resistance	Over $100M \Omega$ at 100V D.C. for 1 minute.	Between coil and core. DC 100V voltage shall be applie 1 minuteacross the top surface and the terminal of th sample(current: 1 m A)			
12.Withstanding voltage	No dielectric breakdown at 100V D.C. for 1 minute	Between coil and core. DC 1 minuteacross the top su sample(current: 1 m A)	100V voltage shall be applied for urface and the terminal of this		
13.Adhesion of terminal electrode	Shall not come off PC board.	The test samples shall be s reflow. Applied force: 10N to X and Solder cream thickness: 0. 10N 10N	soldered to the test board by the d Y directions. Duration: 5s. 12mm. J, 5s		
		Y			
14.Resistance to vibration	Inductance change: Within±10% There shall be no mechanical damage.	hall be no mechanical damage.  reflow.  Then it shall be submitted to  The test samples shall be so reflow.  Then it shall be submitted to  Frequency Range  Total Amplitude  Sweeping Method  Time  Recovery: At least 2hrs of re condition sfter the test, follow 48 hrs.  20% of autfoce of terminal electrode in  The test semples shall be dir			
15.Solderability	At least 90% of surface of terminal electrode is covered by new solder.	The test samples shall be of preheated for 2 minutes in a and after it has been immed for 5.0±1.0 seconds molte Flux: Methanol solution cor Solder Temperature: 245± Immersion depth: 0.5mm.	dipped in flux, and then shall be a temperature of 135~150℃ rsed to a depth 0.5mm below on solder as shown in below table. Intaining rosin 25%. :5℃		

Item	Specified Value	Test Method and Remarks
16.Resistance to	Inductance change: Within±10%	The test sample shall be exposed to reflow oven at 230 $\pm$
soldering heat	No significant abnormality in appearance.	$5^\circ C$ for 40 seconds, with peak temperature at $260\pm5^\circ C$ for
		5 seconds, 2 times.
		Test board thickness: 1.0 mm
		Test board material: glass epoxy-resin.
		Q Reflow condition (temperature chart.)
		300
		250
		ି ନ ନ ନେ କେ ଟେ ଟେ ୧୯ ୧୦ ୧୦ ୧୦ ନେ ନି ନି ନି ନି ନି ନି ନି ନେ ଦେ t(Sec.)
17 Thormal shael	Industance channes Within 1000	The test complex shall be coldered to the test heard by the
		reflow. The test samples shall be placed at specified
	No significant abnormality in appearance.	temperature for specified time by step 1 to step 4 as shown
		in below table in sequence
		The temperature cvcle shall be repeated 100 cvcles.
		Conditions of 1 cycle
		Step Temperature(°C) Duration(min)
		2 Room temperature Within 3
		3 +85+2 30+3
		4 Room temperature Within 3
18.Damp heat	Inductance change: Within $\pm$ 10%	Recovery : At least 2hrs of recovery under the standard
	No significant abnormality in appearance.	condition after the test, followed by the measurement within
		48 hrs.
		The test samples shall be soldered to the test board by the
		reflow.
		The test samples shall be placed in thermostatic oven set at
		specified temperature and humidity as shown in below table.
		I emperature 60±2°C
		Humidity 90~95%RH
		Time 500±24hour
19.Loading under damp	Inductance change: Within+10%	Recovery: At least 2hrs of recovery under the standard
heat	No significant abnormality in appearance.	condition after the test, followed by the measurement within
		48 hrs.
		The test samples shall be soldered to the test board by the
		reflow.
		The test samples shall be placed in thermostatic oven set at
		specified temperature and humidity and applied the rated
		current continuously as shown in below table.
		Temperature 60±2℃
		Humidity 90~95%RH
		Time 500±24hour
	1	



Item	Specified Value	Test Me	ethod and Remarks	
20.Low temperature life	Inductance change: Within±10%	Recovery : At least 2h	rs of recovery under the	standard
test	No significant abnormality in appearance.	condition after the test, fo	blowed by the measurem	ent within
		48 hrs.		
		The test samples shall be	e soldered to the test boa	ard by the
		reflow.		
		After that, the test sample	es shall be placed at test	conditions
		as shown in below table.		
		Temperature	-40±3℃	
		Time	500 $\pm$ 24hour	
21.High temperature life	Inductance change: Within $\pm 10\%$	Recovery : At least 2h	rs of recovery under the	standard
test	No significant abnormality in appearance.	condition after the test, for	bllowed by the measurem	ent within
		48 hrs.		
		Temperature	125±3℃	
		Time	500 $\pm$ 24hour	
22.Loading at high	Inductance change: Within $\pm 10\%$	The test samples shall be	e soldered to the test boa	ard by the
temperature life test	No significant abnormality in appearance	reflow soldering.		
		Temperature	<b>85±3</b> ℃	
		Applied current	Rated current	
		Time	$500\pm24$ hour	
23.Standard condition	Standard test condition : Unless otherwise			
	specified, temperature is 25 $\pm$ 15 $^\circ\!\!\mathbb{C}$ and 65 $\pm$			
	20% of relative humidity.			
	When there are question concerning			
	measurement result : In order to provide			
	correlation date, the test shall be condition of 25			
	$\pm 2^{\circ}$ of temperature. 65 $\pm 5\%$ relative humidity.			
	Inductance is in accordance with our measured			
	value			



Specified value	Test Method and Remarks
ectric no variation Appearance no deformation.	€ Reflow hart endurance test (temperature chart.)
ductance change: Within $\pm 10\%$	300
o significant abnormality in appearance.	The test should be made under the conditions according to the chart, after the test it is kept for 2 hours under the normal temperature and humidity. Then, no mechanical and electrical defect should be found out. The reflow test can be done twice, but the interval should be more than one hour under the normal conditions. The reflow test conditions are based on the testing instruments available in VCOIL.
eddoo	ctric no variation Appearance no deformation. uctance change: Within±10% significant abnormality in appearance.

#### 7. Others:

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7.2. We will not take any responsibility for any troubles caused by usage beyond the range that this document specifies.

7.3. The products in this specification are targeted for use in general electrical equipments. Please do not apply on equipments that need. Especially high reliability and/or the defects caused by the product will have direct influence on a person's life or property.

7.4. Period of quality assurance shall be 1 year from the date of shipment. The products must be controlled normal conditions, thus in cases where the products are put under abnormally high temperature and humidity or contamination and damage by natural disasters or other reasons, the above quality assurance period will not be valid.

7.5. Please return this document with signature of receipt within 30 days after our issued date. In case this document is not returned with signature of receipt within 30 days, it is seen as you have approved this document.

7.6. When additions or modifications are needed to this document, both parties shall discuss the revision of the document.

7.7. Both parties are under confidentiality obligation regarding the information contained in this document.



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